DZ5X068D

Silicon epitaxial planar type

For surge absorption circuits

■ Features

- Excellent rising characteristics of zener current I_Z
- Low zener operating resistance R_Z
- Halogen-free / RoHs compliant
  (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol: 02

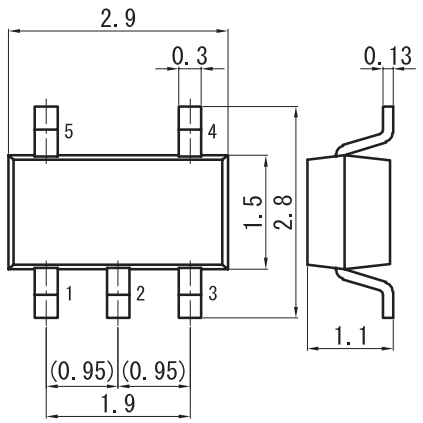
■ Basic Part Number

Dual DZ3X068D (Common anode)

■ Packaging

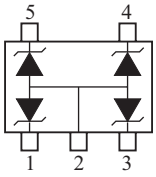
DZ5X068D0R Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

Unit: mm



1: Cathode -1
2: Anode-1, 2, 3, 4
3: Cathode -2
4: Cathode -3
5: Cathode -4

Panasonic	Mini5-G3-B
JEITA	SC-74A
Code	MO-178



■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Total power dissipation *1	P_T	200	mW
Electrostatic discharge *2	ESD	±10	kV
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

Note) ∗1: Mounted on glass epoxy print board. (45 mm × 45 mm × 1 mm)(4 diode total)
Solder in (0.7 mm × 1.0 mm)
∗2: Test method:IEC61000-4-2 (C = 150 pF, R = 330 Ω, Contact discharge:10 times)

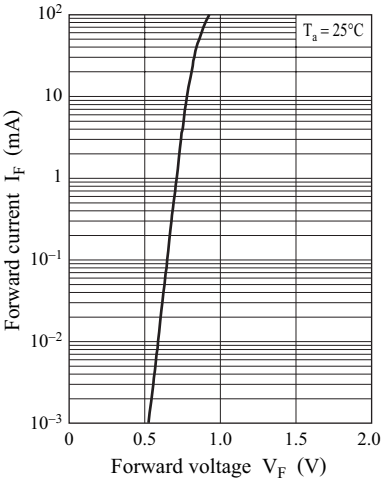
■ Common Electrical Characteristics $T_a = 25°C±3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 10$ mA			1.0	V
Zener voltage *1,2	V_Z	$I_Z = 5$ mA	6.46		7.14	V
Zener operating resistance	R_Z	$I_Z = 5$ mA			30	Ω
Zener rise operating resistance	R_{ZK}	$I_Z = 0.5$ mA			60	Ω
Reverse current	I_R	$V_R = 4.0$ V			0.1	μA
Temparature coefficient of zener voltage *3	S_Z	$I_Z = 5$ mA		3.1		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. ∗1: The temperature must be controlled 25°C for V_Z measurement. V_Z value measured at other temperature must be adjusted to V_Z (25°C)
∗2: V_Z guaranteed 20 ms after current flow.
∗3: T_j = 25°C to 150°C

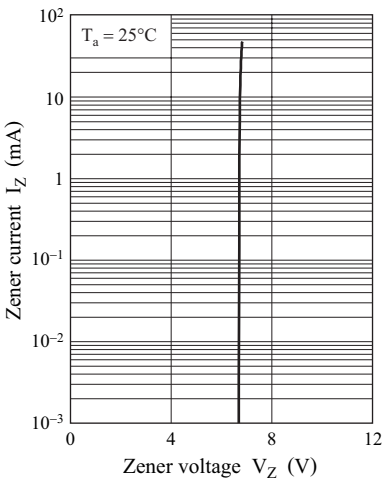
DZ5X068D_IF-VF

I_F — V_F



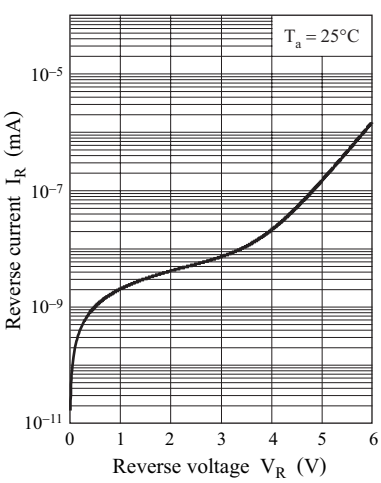
DZ5X068D_IZ-VZ

I_Z — V_Z



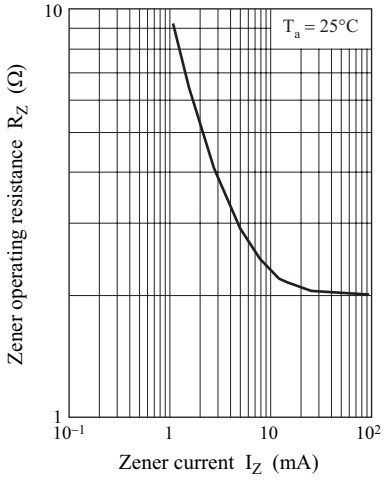
DZ5X068D_IR-VR

I_R — V_R



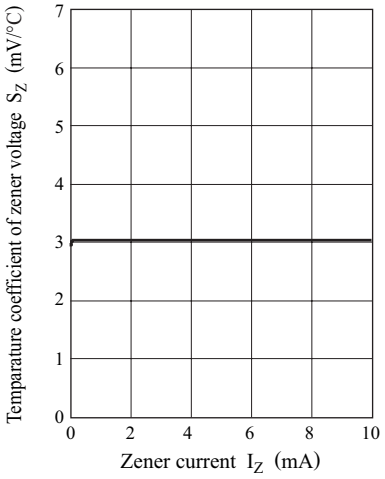
DZ5X068D_RZ-IZ

R_Z — I_Z

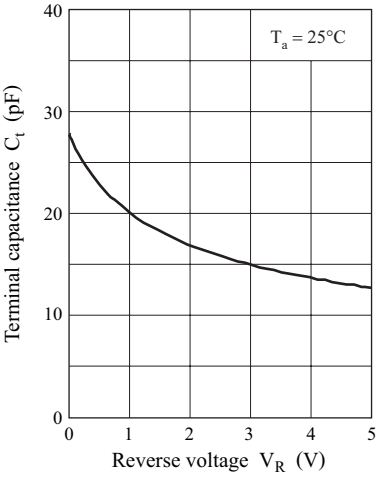


DZ5X068D_SZ-IZ

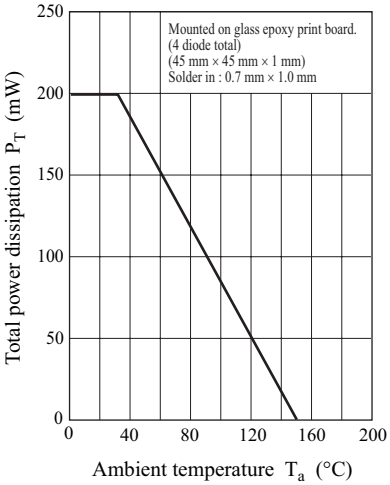
S_Z — I_Z



C_t — V_R

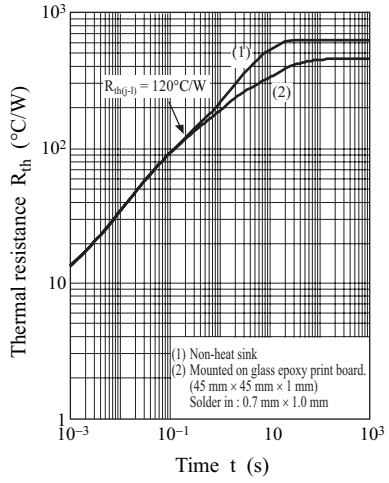


P_T — T_a



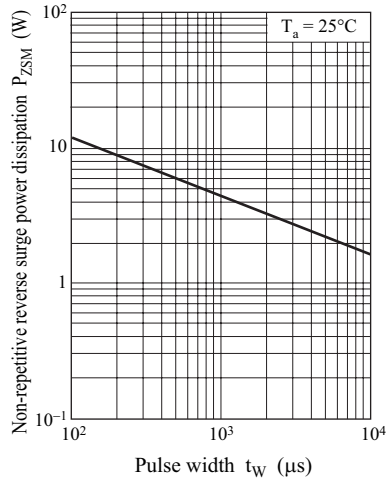
DZ5X__Rth-t

R_{th} — t



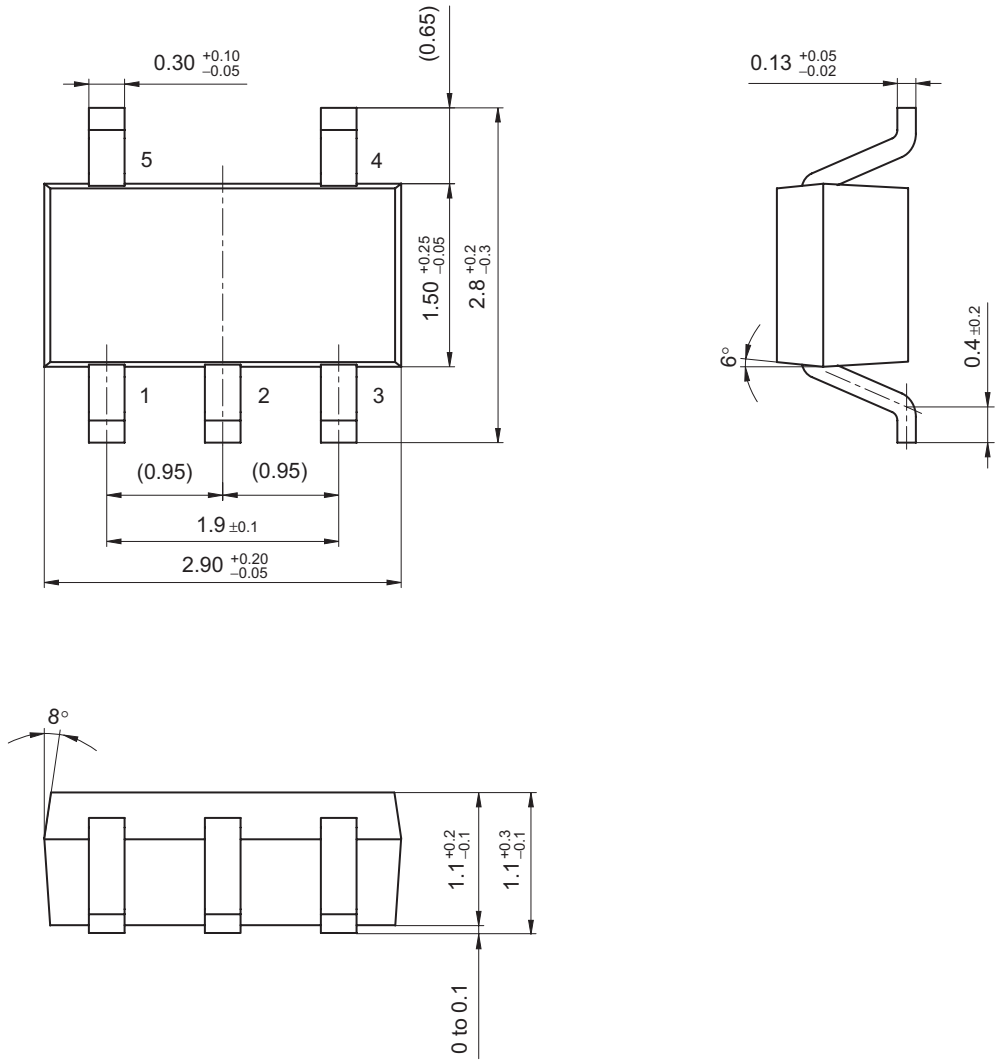
DZ5X__P_{ZSM}-t_W

P_{ZSM} — t_W

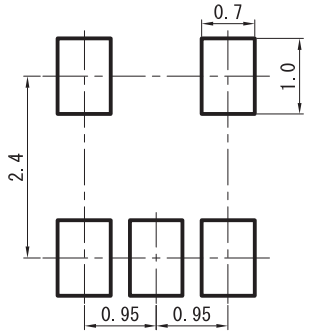


Mini5-G3-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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